



**Absolute Maximum Ratings — Standard Triac**

Symbol	Parameter	Value	Unit		
$I_{T(RMS)}$	RMS on-state current (full sine wave)	Qxx10Ry/ Qxx10Ny	$T_C = 95^\circ\text{C}$	10	A
		Qxx10Ly	$T_C = 90^\circ\text{C}$		
$I_{TSM}$	Non repetitive surge peak on-state current (full cycle, $T_J$ initial = $25^\circ\text{C}$ )	f = 50 Hz	t = 20 ms	100	A
		f = 60 Hz	t = 16.7 ms	120	
$I^2t$	$I^2t$ Value for fusing	$t_p = 8.3$ ms		60	$\text{A}^2\text{s}$
di/dt	Critical rate of rise of on-state current $I_G = 200\text{mA}$ with $\leq 0.1\mu\text{s}$ rise time	f = 120 Hz	$T_J = 125^\circ\text{C}$	70	$\text{A}/\mu\text{s}$
$I_{GTM}$	Peak gate trigger current	$t_p \leq 10 \mu\text{s}$ $I_{GT} \leq I_{GTM}$	$T_J = 125^\circ\text{C}$	1.8	A
$P_{G(AV)}$	Average gate power dissipation		$T_J = 125^\circ\text{C}$	0.5	W
$T_{stg}$	Storage temperature range			-40 to 150	$^\circ\text{C}$
$T_J$	Operating junction temperature range			-40 to 125	$^\circ\text{C}$

**Absolute Maximum Ratings — Alternistor Triac (3 Quadrants)**

Symbol	Parameter	Value	Unit		
$I_{T(RMS)}$	RMS on-state current (full sine wave)	Qxx10LHy	$T_C = 90^\circ\text{C}$	10	A
		Qxx10RHy/ Qxx10NHy	$T_C = 95^\circ\text{C}$		
$I_{TSM}$	Non repetitive surge peak on-state current (full cycle, $T_J$ initial = $25^\circ\text{C}$ )	f = 50 Hz	t = 20 ms	110	A
		f = 60 Hz	t = 16.7 ms	120	
$I^2t$	$I^2t$ Value for fusing	$t_p = 8.3$ ms		60	$\text{A}^2\text{s}$
di/dt	Critical rate of rise of on-state current	f = 120 Hz	$T_J = 125^\circ\text{C}$	70	$\text{A}/\mu\text{s}$
$I_{GTM}$	Peak gate trigger current	$t_p \leq 10 \mu\text{s}$ $I_{GT} \leq I_{GTM}$	$T_J = 125^\circ\text{C}$	2.0	A
$P_{G(AV)}$	Average gate power dissipation		$T_J = 125^\circ\text{C}$	0.5	W
$T_{stg}$	Storage temperature range			-40 to 150	$^\circ\text{C}$
$T_J$	Operating junction temperature range			-40 to 125	$^\circ\text{C}$

**Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise specified) — Standard Triac**

Symbol	Test Conditions	Quadrant	Qxx10x4	Qxx10x5	Unit
$I_{GT}$	$V_D = 12\text{V}$ $R_L = 60 \Omega$	I – II – III IV	25 50	50 75 (TYP)	mA
$V_{GT}$		I – II – III	1.3		V
$V_{GD}$	$V_D = V_{DRM}$ $R_L = 3.3 \text{k}\Omega$ $T_J = 125^\circ\text{C}$	ALL	0.2		V
$I_H$	$I_T = 200\text{mA}$	MAX.	35	50	mA
dv/dt	$V_D = V_{DRM}$ Gate Open $T_J = 125^\circ\text{C}$	400V	150	225	V/ $\mu\text{s}$
		600V	100	200	
		800V	75	175	
	$V_D = V_{DRM}$ Gate Open $T_J = 100^\circ\text{C}$	1000V	50	150	
(dv/dt)c	(di/dt)c = 5.4 A/ms $T_J = 125^\circ\text{C}$	TYP.	2	4	V/ $\mu\text{s}$
$t_{gt}$	$I_G = 2 \times I_{GT}$ PW = 15 $\mu\text{s}$ $I_T = 14.1 \text{A(pk)}$	TYP.	3.0	3.0	$\mu\text{s}$

Note: xx = voltage, x = package, y = sensitivity

**Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise specified) — Alternistor Triac (3 Quadrants)**

Symbol	Test Conditions	Quadrant		Value	Unit
$I_{GT}$	$V_D = 12V$ $R_L = 60 \Omega$	I – II – III	MAX.	50	mA
$V_{GT}$		I – II – III	MAX.	1.3	V
$V_{GD}$	$V_D = V_{DRM}$ $R_L = 3.3 \text{ k}\Omega$ $T_J = 125^\circ\text{C}$	I – II – III	MIN.	0.2	V
$I_H$	$I_T = 100\text{mA}$		MAX.	50	mA
$dv/dt$	$V_D = V_{DRM}$ Gate Open $T_J = 125^\circ\text{C}$	400V	MIN.	750	V/ $\mu\text{s}$
		600V		650	
		800V		500	
	$V_D = V_{DRM}$ Gate Open $T_J = 100^\circ\text{C}$	1000V		300	
(dv/dt)c	(di/dt)c = 5.4 A/ms $T_J = 125^\circ\text{C}$		TYP.	30	V/ $\mu\text{s}$
$t_{gt}$	$I_G = 2 \times I_{GT}$ $PW = 15\mu\text{s}$ $I_T = 14.1 \text{ A(pk)}$		TYP.	4.0	$\mu\text{s}$

**Static Characteristics**

Symbol	Test Conditions		Value	Unit	
$V_{TM}$	$I_{TM} = 14.1\text{A}$ $t_p = 380 \mu\text{s}$		MAX.	1.60	V
$I_{DRM}$ $I_{RRM}$	$V_{DRM} = V_{RRM}$	$T_J = 25^\circ\text{C}$	400 - 600V	10	$\mu\text{A}$
		$T_J = 125^\circ\text{C}$	400 - 800V	2	mA
		$T_J = 100^\circ\text{C}$	1000V	3	

**Thermal Resistances**

Symbol	Parameter		Value	Unit
$R_{\theta(J-C)}$	Junction to case (AC)	Qxx10Ryy/ Qxx10Nyy	1.3	$^\circ\text{C/W}$
		Qxx10Lyy	2.6	
$R_{\theta(J-A)}$	Junction to ambient (AC)	Qxx10Ryy	45	$^\circ\text{C/W}$
		Qxx10Lyy	50	

Note: xx = voltage, x = package, y = sensitivity, yy = type & sensitivity

**Figure 1: Definition of Quadrants**

**Figure 2: Normalized DC Gate Trigger Current for All Quadrants vs. Junction Temperature**

**Figure 3: Normalized DC Holding Current vs. Junction Temperature**

**Figure 4: Normalized DC Gate Trigger Voltage for All Quadrants vs. Junction Temperature**

**Figure 5: Power Dissipation (Typical) vs. RMS On-State Current**

**Figure 6: Maximum Allowable Case Temperature vs. On-State Current**


**Figure 7: Maximum Allowable Ambient Temperature vs. On-State Current**



**Figure 8: On-State Current vs. On-State Voltage (Typical)**



**Figure 9: Surge Peak On-State Current vs. Number of Cycles**



### Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		5°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		5°C/second max
Reflow	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260 <sup>+0/-5</sup> °C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes Max.
Do not exceed		280°C



### Physical Specifications

<b>Terminal Finish</b>	100% Matte Tin-plated
<b>Body Material</b>	UL recognized epoxy meeting flammability classification 94V-0.
<b>Terminal Material</b>	Copper Alloy

### Design Considerations

Careful selection of the correct device for the application's operating parameters and environment will go a long way toward extending the operating life of the Thyristor. Good design practice should limit the maximum continuous current through the main terminals to 75% of the device rating. Other ways to ensure long life for a power discrete semiconductor are proper heat sinking and selection of voltage ratings for worst case conditions. Overheating, overvoltage (including dv/dt), and surge currents are the main killers of semiconductors. Correct mounting, soldering, and forming of the leads also help protect against component damage.

### Environmental Specifications

Test	Specifications and Conditions
<b>AC Blocking</b>	MIL-STD-750, M-1040, Cond A Applied Peak AC voltage @ 125°C for 1008 hours
<b>Temperature Cycling</b>	MIL-STD-750, M-1051, 100 cycles; -40°C to +150°C, 15-min dwell-time
<b>Temperature/Humidity</b>	EIA/JEDEC, JESD22-A101 1008 hours; 320V - DC: 85°C; 85% rel humidity
<b>High Temp Storage</b>	MIL-STD-750, M-1031, 1008 hours; 150°C
<b>Low-Temp Storage</b>	1008 hours; -40°C
<b>Thermal Shock</b>	MIL-STD-750, M-1056 10 cycles; 0°C to 100°C; 5-min dwell time at each temperature; 10 sec (max) transfer time between temperature
<b>Autoclave</b>	EIA/JEDEC, JESD22-A102 168 hours (121°C at 2 ATMs) and 100% R/H
<b>Resistance to Solder Heat</b>	MIL-STD-750 Method 2031
<b>Solderability</b>	ANSI/J-STD-002, category 3 Test A
<b>Lead Bend</b>	MIL-STD-750, M-2036 Cond E

**Dimensions — TO-220AB (R-Package) — Non-Isolated Mounting Tab Common with Center Lead**



Note: Maximum torque to be applied to mounting tab is 8 in-lbs. (0.904 Nm).

Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.380	0.420	9.65	10.67
B	0.105	0.115	2.67	2.92
C	0.230	0.250	5.84	6.35
D	0.590	0.620	14.99	15.75
E	0.142	0.147	3.61	3.73
F	0.110	0.130	2.79	3.30
G	0.540	0.575	13.72	14.61
H	0.025	0.035	0.64	0.89
J	0.195	0.205	4.95	5.21
K	0.095	0.105	2.41	2.67
L	0.060	0.075	1.52	1.91
M	0.085	0.095	2.16	2.41
N	0.018	0.024	0.46	0.61
O	0.178	0.188	4.52	4.78
P	0.045	0.060	1.14	1.52
R	0.038	0.048	0.965	1.22

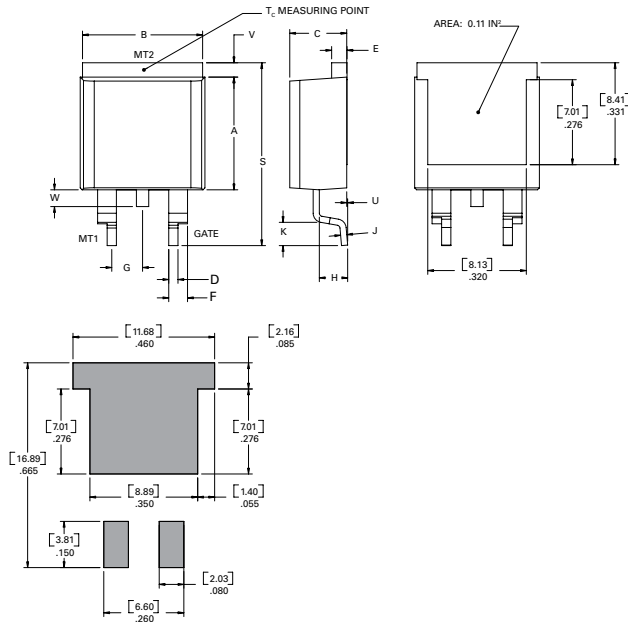
**Dimensions — TO-220AB (L-Package) — Isolated Mounting Tab**



Note: Maximum torque to be applied to mounting tab is 8 in-lbs. (0.904 Nm).

Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.380	0.420	9.65	10.67
B	0.105	0.115	2.67	2.92
C	0.230	0.250	5.84	6.35
D	0.590	0.620	14.99	15.75
E	0.142	0.147	3.61	3.73
F	0.110	0.130	2.79	3.30
G	0.540	0.575	13.72	14.61
H	0.025	0.035	0.64	0.89
J	0.195	0.205	4.95	5.21
K	0.095	0.105	2.41	2.67
L	0.060	0.075	1.52	1.91
M	0.085	0.095	2.16	2.41
N	0.018	0.024	0.46	0.61
O	0.178	0.188	4.52	4.78
P	0.045	0.060	1.14	1.52
R	0.038	0.048	0.965	1.22

**Dimensions — TO-263AA (N-Package) — D<sup>2</sup>-PAK Surface Mount**



Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.360	0.370	9.14	9.40
B	0.380	0.420	9.65	10.67
C	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
E	0.045	0.060	1.14	1.52
F	0.060	0.075	1.52	1.91
G	0.095	0.105	2.41	2.67
H	0.092	0.102	2.34	2.59
J	0.018	0.024	0.46	0.61
K	0.090	0.110	2.29	2.79
S	0.590	0.625	14.99	15.88
V	0.035	0.045	0.89	1.14
U	0.002	0.010	0.05	0.25
W	0.040	0.070	1.016	1.78

**Product Selector**

Part Number	Voltage (xx)				Gate Sensitivity Quadrants		Type	Package
	400V	600V	800V	1000V	I – II – III	IV		
Qxx10L4	X	X	X	X	25 mA	50 mA	Standard Triac	TO-220L
Qxx10R4	X	X	X	X	25 mA	50 mA	Standard Triac	TO-220R
Qxx10N4	X	X	X	X	25 mA	50 mA	Standard Triac	TO-263 D <sup>2</sup> -PAK
Qxx10L5	X	X	X	X	50 mA		Standard Triac	TO-220L
Qxx10R5	X	X	X	X	50 mA		Standard Triac	TO-220R
Qxx10N5	X	X	X	X	50 mA		Standard Triac	TO-263 D <sup>2</sup> -PAK
Qxx10LH5	X	X	X	X	50 mA		Alternistor Triac	TO-220L
Qxx10RH5	X	X	X	X	50 mA		Alternistor Triac	TO-220R
Qxx10NH5	X	X	X	X	50 mA		Alternistor Triac	TO-263 D <sup>2</sup> -PAK

**Packing Options**

Part Number	Marking	Weight	Packing Mode	Base Quantity
Qxx10L/Ryy	Qxx10L/Ryy	2.2 g	Bulk	500
Qxx10L/RyyTP	Qxx10L/Ryy	2.2 g	Tube Pack	500 (50 per tube)
Qxx10NyyTP	Qxx10Nyy	1.6 g	Tube	500 (50 per tube)
Qxx10NyyRP	Qxx10Nyy	1.6 g	Embossed Carrier	500

Note: xx = voltage, yy = type & sensitivity





## Данный компонент на территории Российской Федерации

### Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

moschip.ru

moschip.ru\_4

moschip.ru\_6

moschip.ru\_9